

DF15005M - DF1510M

Features

- Glass Passivated Die Construction
- Low Forward Voltage Drop, High Current Capability
- Surge Overload Rating to 50A Peak
- Designed for Printed Circuit Board Applications
- UL Listed Under Recognized Component Index, File Number E94661
- Lead Free Finish, RoHS Compliant (Date Code 0532+) (Note 3)

DF-M							
Dim	Min	Max					
Α	7.40	7.90					
В	6.20	6.50					
C	0.22	0.30					
D	1.27	2.03					
E	7.60	8.90					
G	3.81	4.69					
н	8.13	8.51					
7	2.40	3.40					
K	5.00	5.20					
	0.46	0.58					
All Dimensions in mm							

Mechanical Data

Case: DF-M

Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0

Moisture Sensitivity: Level 1 per J-STD-020C

Terminals: Finish — Tin. Solderable per MIL-STD-202, Method 208 @3:

Polarity: As Marked on Case Marking: Type Number

Weight: 0.38 grams (approximate)

Maximum Ratings and Electrical Characteristics

@TA = 25°C unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

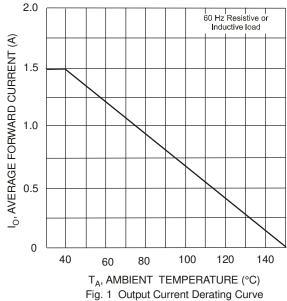
Characteristic	Symbol	DF 15005M	DF 1501M	DF 1502M	DF 1504M	DF 1506M	DF 1508M	DF 1510M	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	50	100	200	400	600	800	1000	V
RMS Reverse Voltage	V _{R(RMS)}	35	70	140	280	420	560	700	V
Average Rectified Output Current @ T _A = 40°C	lo				1.5				Α
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I _{FSM}				50				Α
Forward Voltage (per element) @ I _F = 1.5A	V_{FM}				1.1				٧
Peak Reverse Current @ T _A = 25°C at Rated DC Blocking Voltage @ T _A = 125°C	I _{RM}				10 500				μΑ
I ² t Rating for Fusing (t<8.3ms)	l ² t				10.4				A ² s
Typical Total Capacitance (Note 2)	C _T				25				pF
Typical Thermal Resistance Junction to Ambient	$R_{\theta JA}$				40				°C/W
Operating and Storage Temperature Range	T _{j,} T _{STG}			-6	5 to +15	0			°C

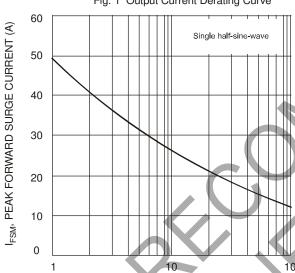
Notes:

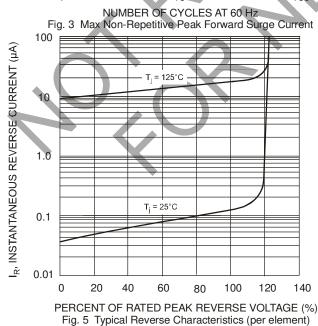
- Thermal resistance from junction to ambient mounted on PC board with 13 x 13mm (0.03mm thick) land areas.
- Measured at 1.0 MHz and applied reverse voltage of 4.0V DC.
- 3. RoHS revision 13.2.2003. Glass and high temperature solder exemptions applied, see EU Directive Annex Notes 5 and 7.

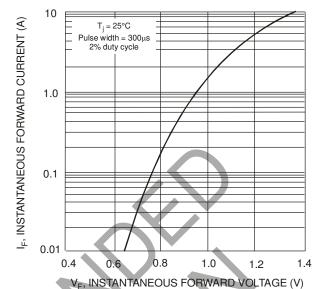


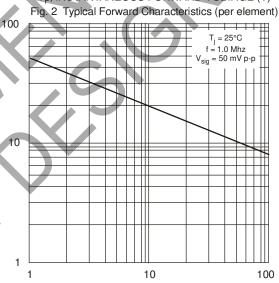
NOT RECOMMENDED FOR NEW DESIGN











V_R, REVERSE VOLTAGE (V) Fig. 4 Typical Total Capacitance (per element)

T, CAPACITANCE (pF)



NOT RECOMMENDED FOR NEW DESIGN

Ordering Information (Note 4)

ĺ	Device	Packaging	Shipping
	DF15xxM	DF-M	50 per Tube

Notes: 4. For packaging details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

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